

## Method for Assembling Microdevices and Related Apparatus

The technology is a process for assembling surface micro-machined parts into larger structures. The parts are connected either to the wafer surface or to each other through hinges, about which the parts are free to rotate.

### Applications

Platform technology for automating the assembly of MEMS devices.

### Advantages

Currently, assembly is performed manually. This technology would make assembly considerably less expensive and more efficient.

### Inventors

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### Intellectual Property Status

US provisional patent application  
filed August 2001.

### Partnering Opportunity

Available for co-development or  
licensing (exclusive or non-  
exclusive) by jurisdiction and/or field  
of use.

### Contact

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